

## FEATURES

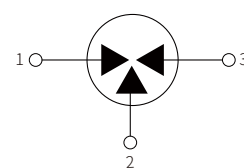
- | Size Design  $\Phi 6.0 \times 8.0 \text{mm}$
- | High Current Handling Capability 10,000A @ 8/20  $\mu\text{s}$
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



$\Phi 6.0 \times 8.0 \text{mm}$



## APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.



Schematic Symbol

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)	100V/s	184-276	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq 800$	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq 700$	V
Impulse Discharge Current 2)	8/20 $\mu$ s	10	KA
Insulation Resistance	DC=100V	$\geq 1$	G $\Omega$
Capacitance at 1MHz	$V_{DC}=0.5V$	$\leq 2$	pF
Operating and Storage Temperature		-40~125	°C

1) In ionized mode

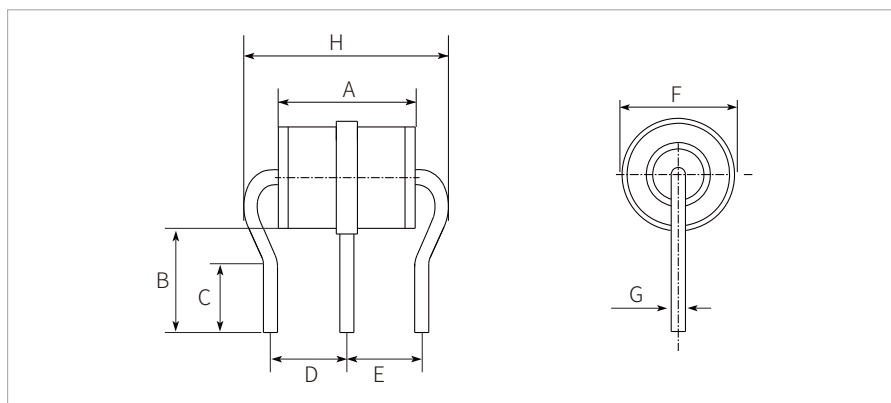
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260°C; Time of dip soldering:10s,1time

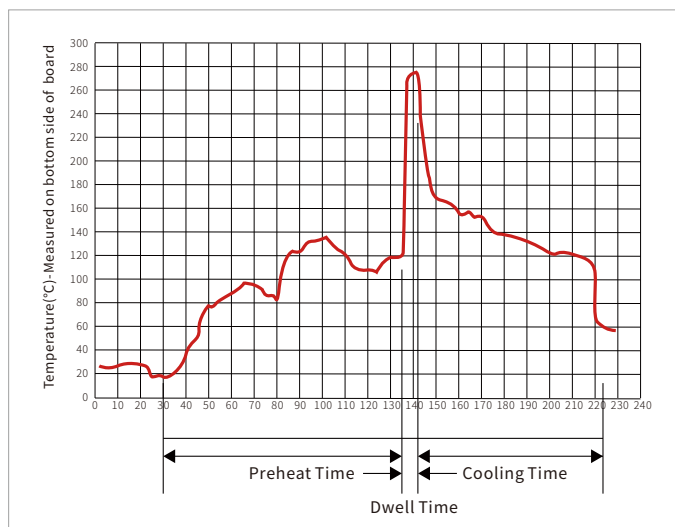
**NOTE:**Up-screen program can be specified by customer' s request via contacting Semiware service

## PRODUCT DIMENSIONS



Ref.	Outline Dimensions
	Millimeters
A	8.0 $\pm$ 0.3
B	5.0 $\pm$ 1.0
C	3.3 $\pm$ 0.3
D	4.4 $\pm$ 0.3
E	4.4 $\pm$ 0.3
F	$\Phi$ 6.0 $\pm$ 0.2
G	$\Phi$ 0.8
H	11 $\pm$ 1

## WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

## ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs		
			Tray	Inner Box	Carton
SG3R06B230	Φ6.0*8.0mm	SG3R06B230	100	500	6000

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**By QR Code**

Website



Wechat

To find your local partner within Semiware' s global website: [www.semiware.com](http://www.semiware.com)

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